

EMAP2007 -- **International Symposium on Electronic Materials and Packaging**

November 19-22, 2007

KAIST (Korea Advanced Institute of Science & Technology), Daejeon, Korea

You are invited to submit a paper for the EMAP2007. The EMAP2007 symposium is organized by KAIST in collaboration with the Center for Electronic Packaging Materials (CEPM). It is jointly sponsored by the IEEE CPMT Daejeon Chapter, IMAPS-Korea, Korea Society of Mechanical Engineers, Korea Society of Electric Engineers, and ASME Korea Section. The objective of this symposium is to create an international forum for the exchange, dissemination and discussion of state-of-the-art technologies and recent developments in electronic materials, packaging and assembly. Following the tremendous success in the last eight conferences in Singapore, Hong Kong, Korea, Taiwan, Malaysia and Japan, which were attended by delegates from more than 10 major countries, the ninth symposium will be held again at the KAIST campus at Daejeon Korea. So come and meet world-renowned authorities from the Asia-Pacific region, USA and Europe. Join us and get in touch with leading-edge electronics packaging technologies, and find out more about Korea's electronics packaging industries. In addition, short courses on current packaging trends and technological issues will be also offered. Papers are invited from industry participants as well as researchers from the academia and government research organizations.

Call for Papers (abstracts due **July 31**)

Major Topics of the Symposium:

- Advanced Electronic Packaging Technologies: WLP, Flip Chip, CSP, SIP, SOP, 3-D
- Packaging Materials and Processes: Lead-free Solders, Adhesives, Underfills, Encapsulants, PCBs
- Interconnect Technologies: Wire bonding, Fine Pitch, Micro via, Build-up Technologies
- Materials Characterization, Testing and Measurements: Electrical, Thermal, Chemical, Mechanical
- Package Design, Modeling and Simulation
- Sensors/Bio/MEMS Packaging
- Reliability and Failure Analysis: Interfacial Phenomena, Delamination, Moisture effects
- Polymers and Ceramics for Electronic Applications, Thin films/coatings, Metallization

Abstracts and Papers

A one-page 300-word abstract should be submitted to the Secretariat of the Symposium, describing the scope, contents and key points of the proposed paper. Instructions for preparing the full paper will be sent to the authors whose abstracts are accepted after review. Participants will be required to register upon notification of acceptance of their full papers. The detailed conference information will be announced later at the website, emap.kaist.ac.kr. If you have any questions, please send an e-mail to emap@kaist.ac.kr.

*Institute of Electrical and Electronics Engineers, Inc.
Phoenix Section CPMT Chapter & Waves and Devices
Chapter Present an all-day Workshop on:*

Emerging Device & Packaging Technologies

The semiconductor industry is entering an era with tremendous opportunities to exploit emerging technologies for the benefit of widely diverse markets. Moore's Law requires increasingly intensive materials innovations to maintain its momentum. Meanwhile, new markets in the areas of bioelectronics, sensors, etc., are leveraging the existing manufacturing infrastructure while incorporating new materials and techniques. This one-day workshop will bring together experts from industry, academia, research labs, and consortia to share their technology roadmaps and visions, novel materials and methods, and discuss technical opportunities. The status and challenges facing device, interconnect, and packaging technologies will be discussed in depth. An expert panel discussion will bring a closure to the day's workshop. Vendors will be on hand to exhibit products and services in all aspects of the supply chain for IC, packaging, and module design and manufacturing.

Date: Friday, November 9th, 2007

Time: 7:00 A.M. – 5:00 P.M.

Location: Arizona State University, Tempe, AZ USA

Topics

- Nanotechnology and Continuum Model Limits
- ITRS Roadmap Challenges
- SiP: 3D, Modules, Discrete Passives Integration
- Flexible Electronics
- Green Materials and Packaging
- Bioelectronics and Sensors Technologies
- General Industry and Technology Visions
- Panel Discussion on Future Challenges and Opportunities for Emerging Technologies

For General Information, visit:

www.ieee.org/phoenix

For Additional Information, contact:

Dr. Vasu Atluri (Chair), +1-480-554-0360

Dr. Chuck Weitzel (Co-Chair), +1-480-413-5906

For Workshop Registration Forms:

Sergio Pacheco, +1-480-413-3737

For Vendor Registration Forms:

Vladimir Noveski, +1-480-554-2375